Call for Participation

ASP-DAC 2026
31st Asia and South Pacific Design Automation Conference

ASIA SOUTH PACIFIC DESIGN AUTOMATION CONFERENCE

Date: Jan. 19-22, 2026
Place: Hong Kong Disneyland Hotel
Early Registration Due: Friday, December 12, 2025 (AOE)

Registration Site: https://www.aspdac.com/aspdac2026/reg

Aims of the Conference

ASP-DAC is the largest conference in Asia and South-Pacific regions on Electronic Design Automation (EDA) area for VLSI and systems. ASP-DAC has been started at 1995 and this ASP-DAC 2026 is 31st conference. ASP-DAC 2026 offers you an ideal opportunity to touch the recent technologies and the future directions on the LSI design and design automation areas by technical papers and tutorials. ASP-DAC also holds Designers' Forum to make presentations about the latest designs for designers. Please do not miss ASP-DAC 2026.

Features of ASP-DAC 2026

▪ Keynote Speeches

1. **January 20: Chenming Hu** (University of California, Berkeley), "FinFET - from Lab to Foundry to EDA/Fabless"; **Yiran Chen** (Duke University), "Edge AI: Everything, Everywhere, All at Once"; **Patrick Groeneveld** (Stanford University), "When Moore Surpasses Mind: The Impact of 6 decades of Relentless Design Automation"
2. **January 21: Yuan Xie** (Hong Kong University of Science and Technology), "From 2D IC to 3D IC and Chiplet : A Retrospective View"; **Charles Alpert** (Cadence Design Systems, Inc.), "Harnessing Agentic AI to Accelerate Designer Productivity"
3. **January 22: Jim Chang** (3DIC Design Methodology Development, TSMC), "Unlocking Hyper-Scale AI: Navigating the Future of 3DIC Design Solutions"; **Takefumi Miyoshi** (e-trees.Japan, Inc., The University of Osaka, QuEL, Inc.), "Design and Implementation of Control System for Quantum Computers"

▪ Tutorials

ASP-DAC 2026 offers attendees a set of 3 hours intense introductions to specific topics. If you register for the conference, you have the option to select two out of the six topics.
Tutorial-1: On-Device AI to Better Mobile and Implantable Devices in Healthcare
Tutorial-2: Design Methodologies and Toolchains for Compute-in-Memory: From Architectures to Systems
Tutorial-3: Design Automation for the Early Fault Tolerant Quantum Computing
Tutorial-4: Bi-Directional Synergy: A Tutorial on Hardware Design for Agentic AI and Agentic AI for Hardware Design
Tutorial-5: APS: An MLIR-Based Hardware-Software Co-design Framework for Agile Processor Specialization
Tutorial-6: Post-Silicon Validation & Hardware Security in Modern Processors

▪ Designers' Forum

Designers' Forum is conceived as a unique program that shares the design experience and solutions of real product developments among LSI designers and EDA academia/developers. This forum will take place on January 21 and 22. This year has 4 oral sessions:
Designer Forum 1: Toward Autonomous Chip Design: From Foundation Models to Agentic EDA;
Designer Forum 2: AI in Production EDA: Digital, Custom, and Manufacturing Use Cases;
Designer Forum 3: Chiplets Go Mainstream: Design Automation for 2.5D/3D Systems;
Panel: AI Accelerators at a Crossroads: Who Will Power the Next Decade of AI?

▪ University LSI Design Contest

In University LSI Design Contest, state-of-the-art LSI and/or system designs compete on their design excellence and implementation quality. 7 high-quality designs all including actual measurement proof will be introduced at the design contest session on **January 20**.

▪ Technical Sessions

There are 187 high quality papers selected from 625 submissions. We also plan 6 special sessions: "100 Years of the FET: From Technology Foundations to EDA Innovation", "From Uniform to Adaptive: The Precision-Scalable Computing Era for Edge Intelligence", "Design Automation for Quantum Error Correction: From Algorithms to Architectures", "Advances in AI-Driven Circuit Verification and Reliability Analysis", "Toward Fully Automated DTCO: ML Frameworks across Technology, Cell, and Library Layers", "From Solvers to Layout: Cross-Layer Approaches for Reliable and Scalable IC Design"

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Conference Secretariat
aspdac2026@aspdac.com

https://www.aspdac.com